



Status of CBM-XYTER Development

Latest Results of the CSA/ADC Test-Chip



Tim Armbruster

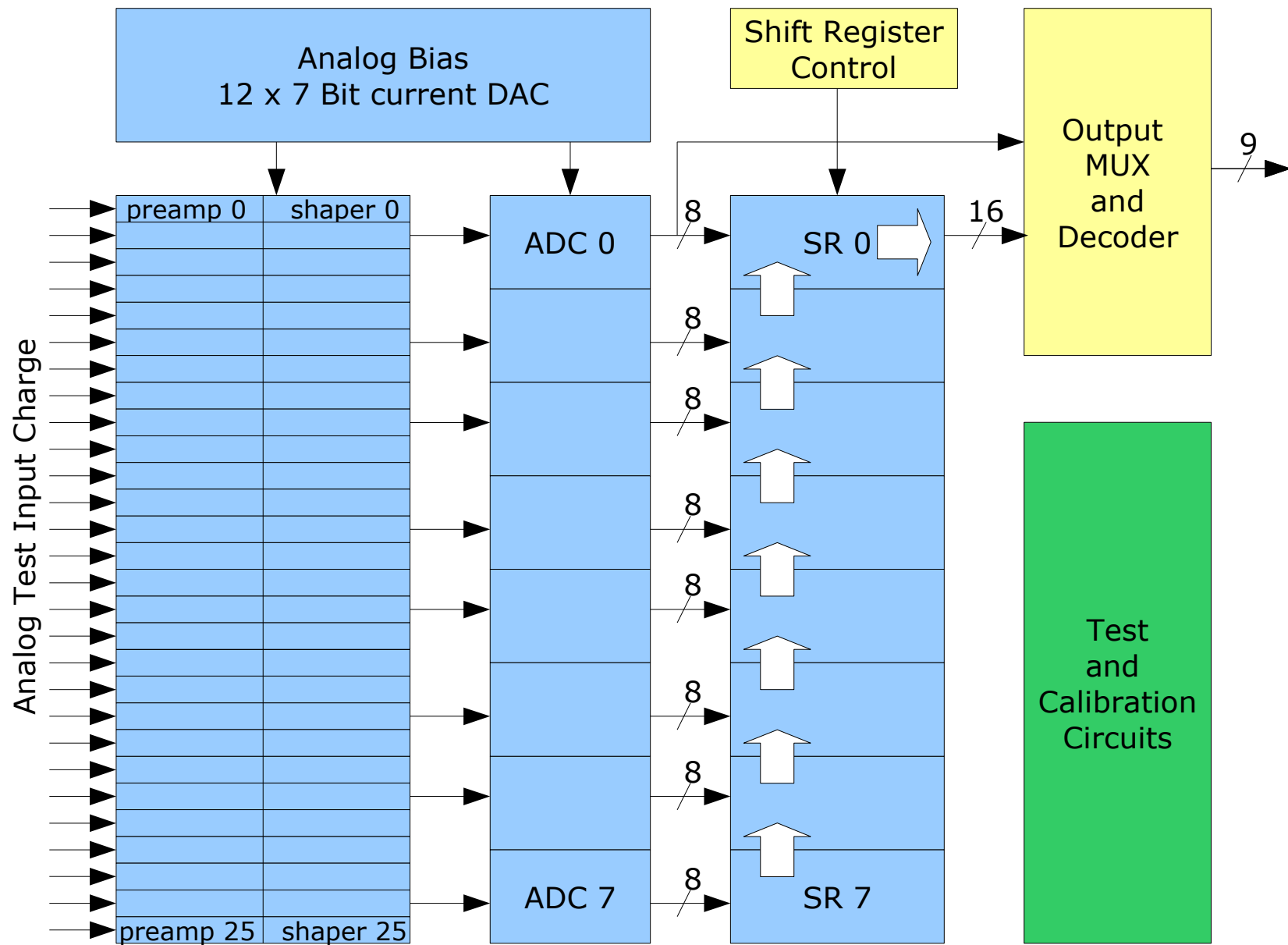
tim.armbruster@ziti.uni-heidelberg.de

14th CBM CM Split

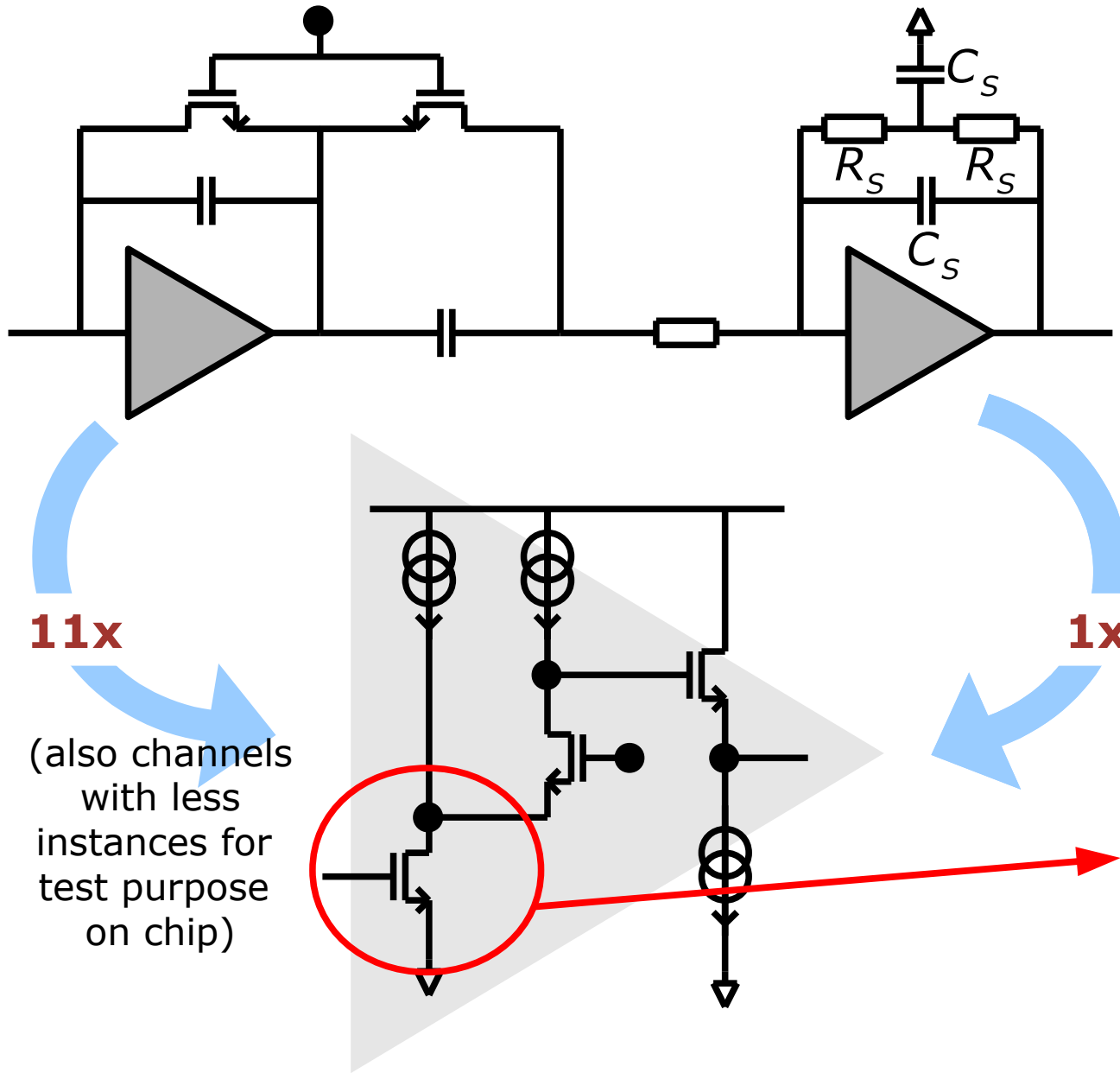
October 2009

- Reminder: Last Test-Chip
 - 1x1 Mini@sic blocks ($1.5 \times 1.5 \text{ mm}^2$), UMC $0.18\mu\text{m}$
 - 26 channels (injection, preamp/shaper, discriminator)
 - Results: power, bias, pulse-shapes, ... good, but measured noise much worse than in simulation
- This talk: Design + results of the new prototype ASIC
 - 1x2 Mini@sic blocks ($1.5 \times 3.2 \text{ mm}^2$), UMC $0.18\mu\text{m}$
 - 26 channels (injection, preamp/shaper, discriminator)
 - Refined layout + smaller schematic improvements
 - 3 different types of input N-MOS (normal, no-triwell, long)
 - New: 8 pipelined 9 Bit ADCs
 - Algorithmic processing based on novel current storage cell
 - Dynamic 3 transistor storage cell matrix
 - Synthesized readout logic and decoder

Current Prototype: Architecture Overview



Reminder: Preamplifier/Shaper Circuit



$$H(s) \approx \frac{A_{DC}}{(1 + sR_S C_S)^2}$$

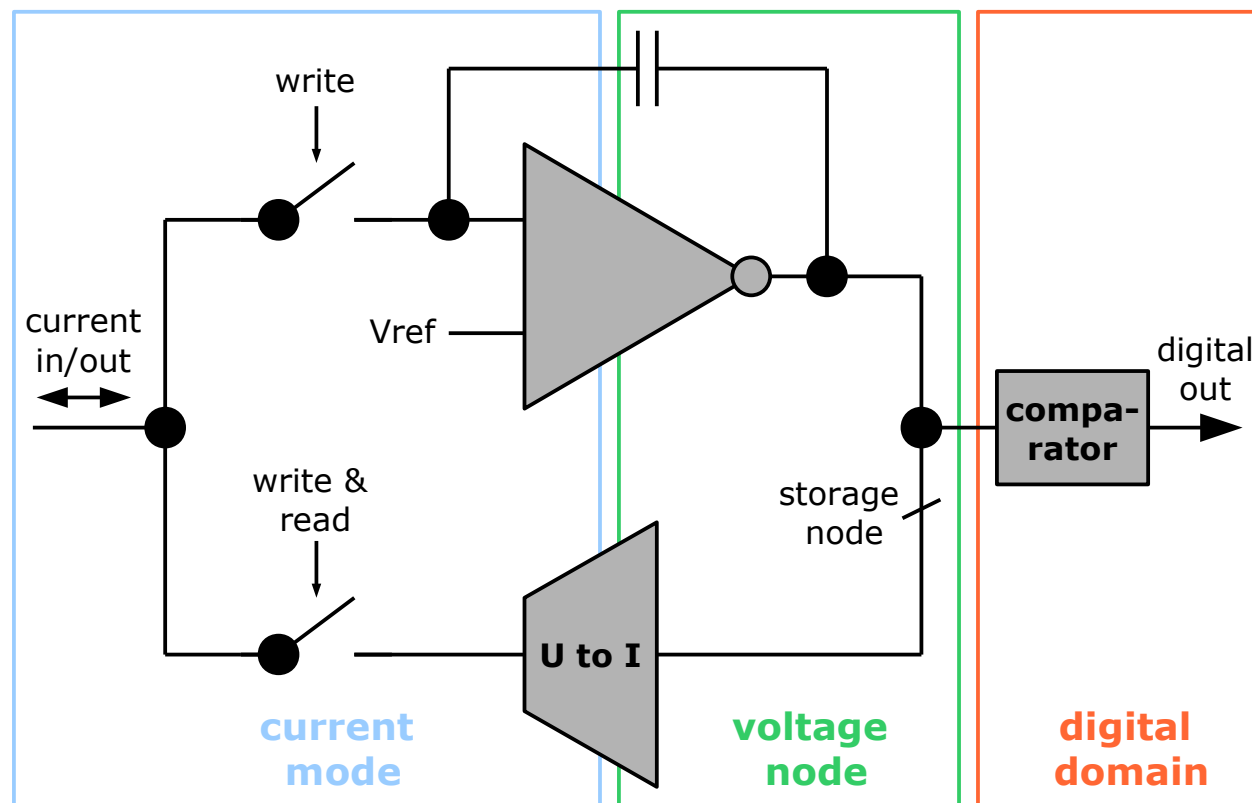
- O'Connor FB
- 2nd order shaper
- Shaping time: 82 ns
- Unified amplifier cell
- N-MOS input
- ≈ 3.6 mW/channel

New: For noise analysis: 3 different input NMOS types

- normal: NMOS, triwell, 180nm length
- no-triwell: NMOS, no-triwell, 180nm length
- long: NMOS, triwell, 320nm length

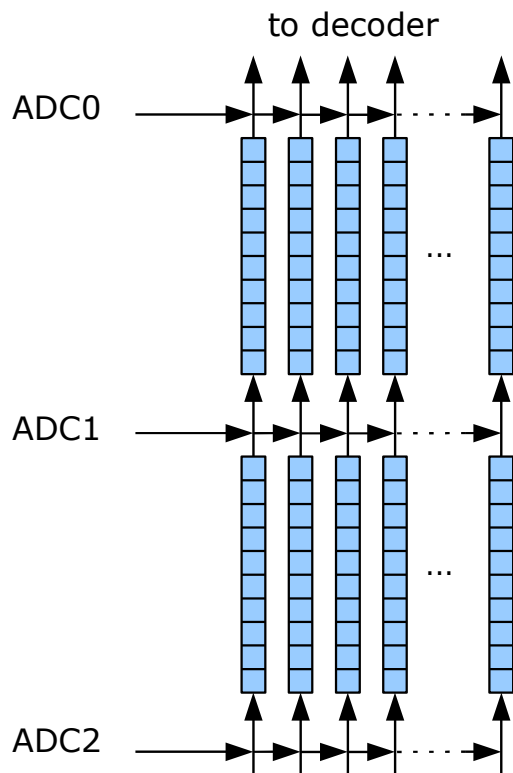
Ivan's Algorithmic ADC Design

- 8 (scaled) pipeline stages, therefore 9 Bit design
- Algorithmic working principle ("1.5 redundant Bits" / conversion step)
- 25 MSamples/s, layout only 130x120 μm^2 , power consumption 4.5 mW
- Core unit: Novel current storage cell:

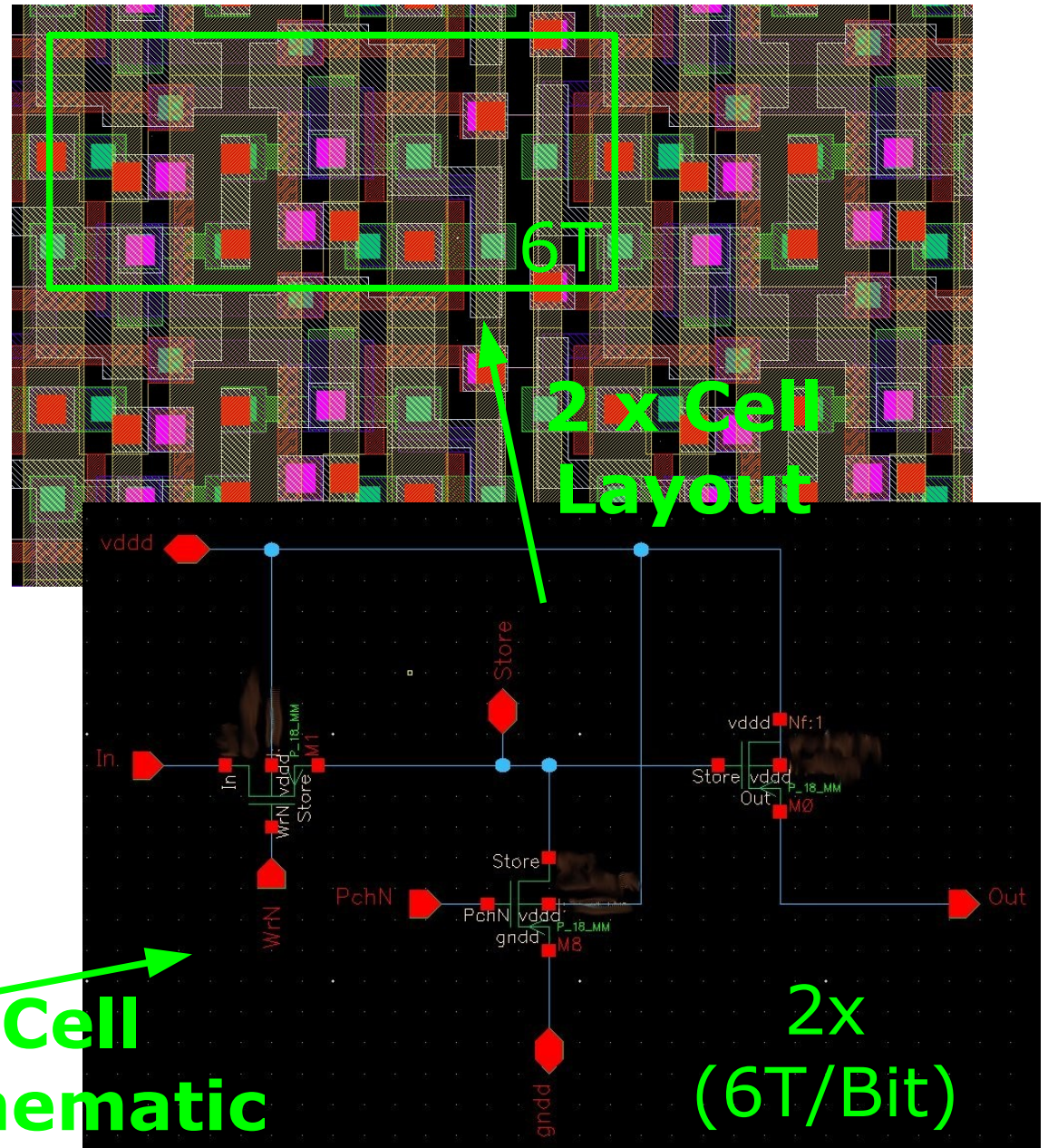


Readout Buffer: Shift Register Matrix

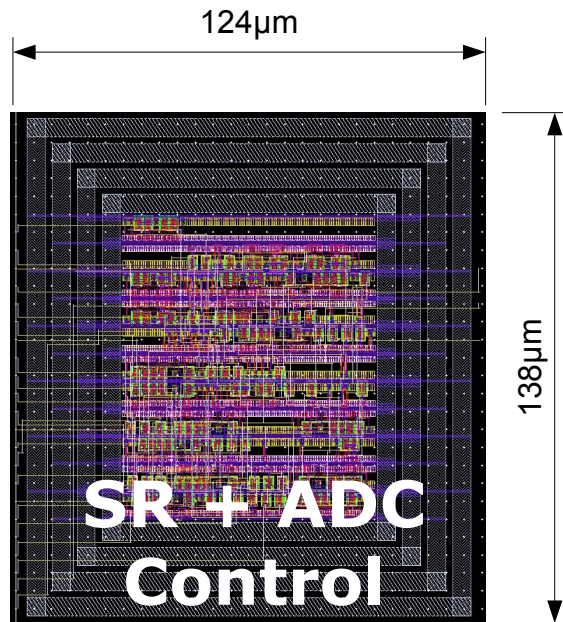
- Shift register matrix can hold the last 40 ADC output values
- Shift registers of all ADCs connected in series during readout
- Small and compact: dynamic 3 transistor storage cell, only 6 transistors per SR-Bit
- Total memory of 5.3 kBit on chip



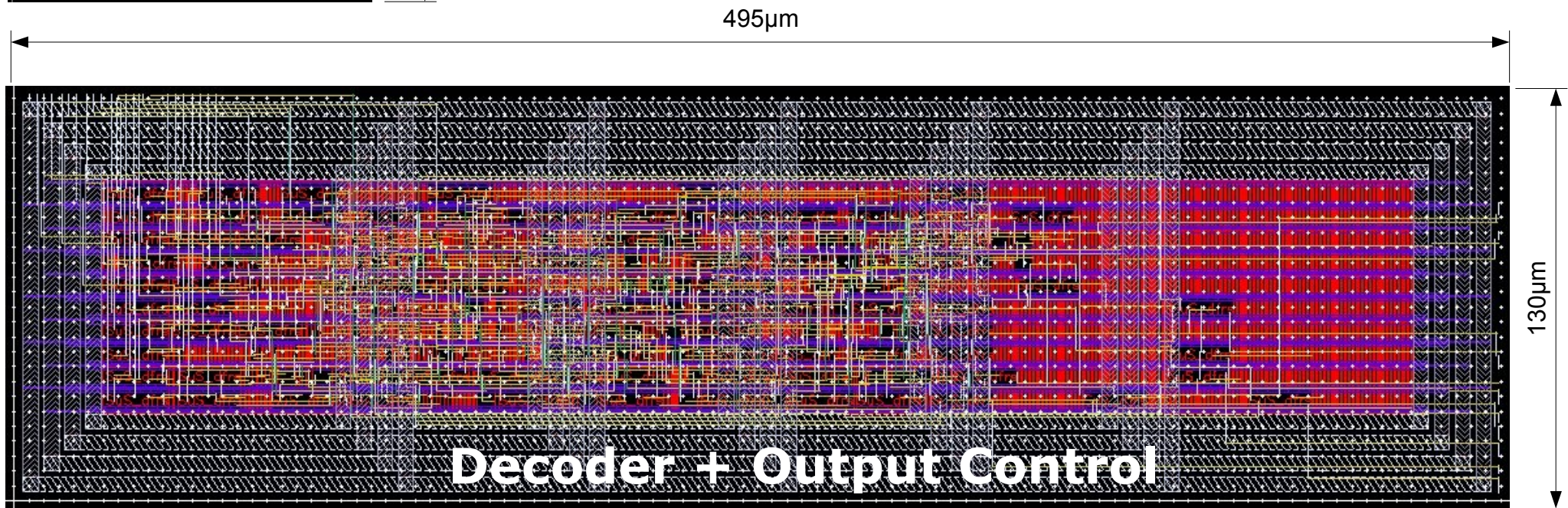
Cell Schematic



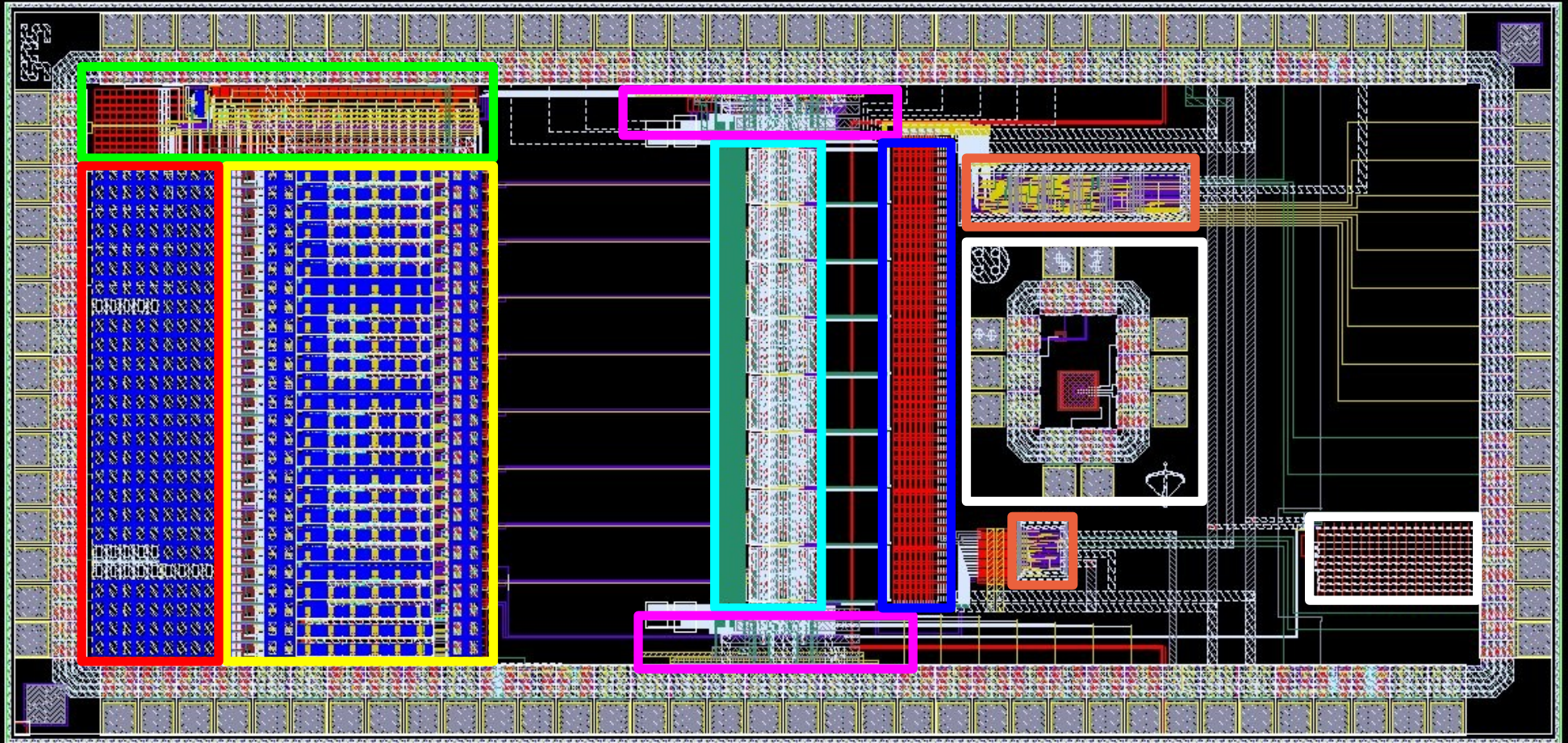
Control + Decoder Logic: Synthesized CMOS Logic



- Two synthesized blocks using our radiation-tolerant standard cell library
- Main CLK frequency is 200 MHz
- Shift Register + ADC Control: Several ADC + SR control signals and hit trigger logic
- Decoder + Output Control: redundant signed binary to signed binary converter, output multiplexer,...



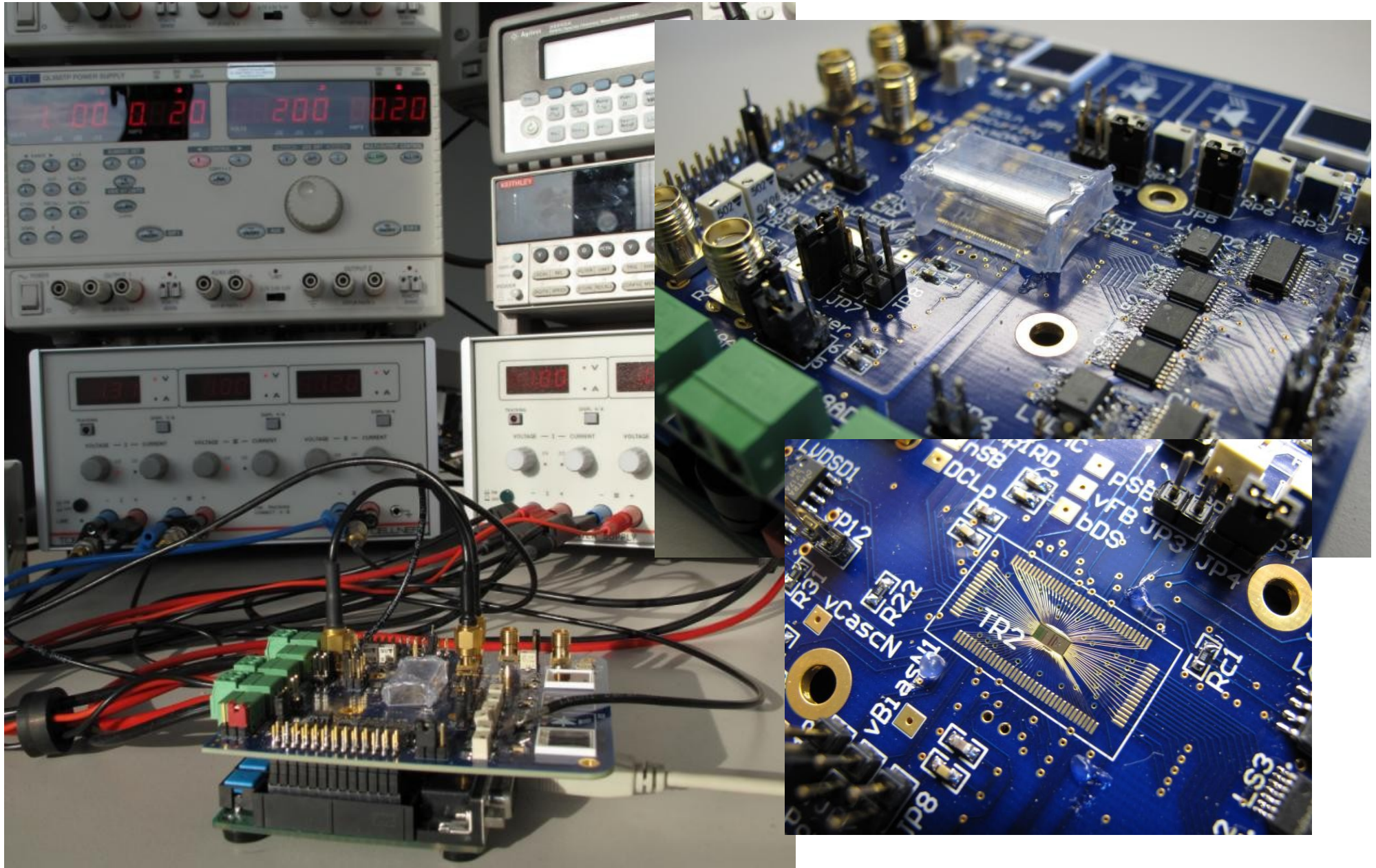
Layout



Bias circuitry (12 current DACs)
26 preamp/shaper channels
Detector capacitors (5pF per block)
8 pipelined ADCs

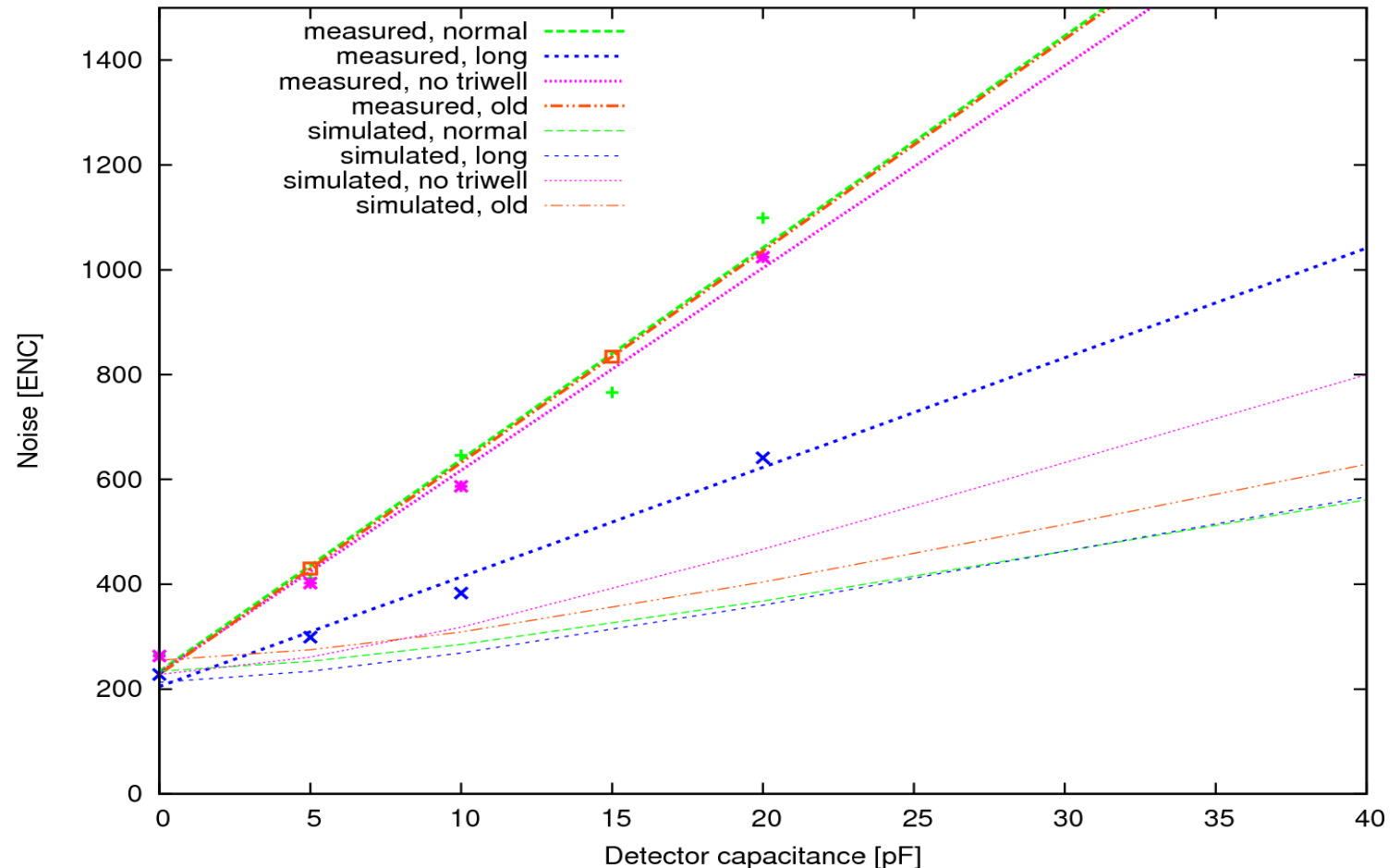
ADC control + bias
5.2 kBit shift register matrix
Control + readout/decoder logic blocks
Test circuits

Test Setup



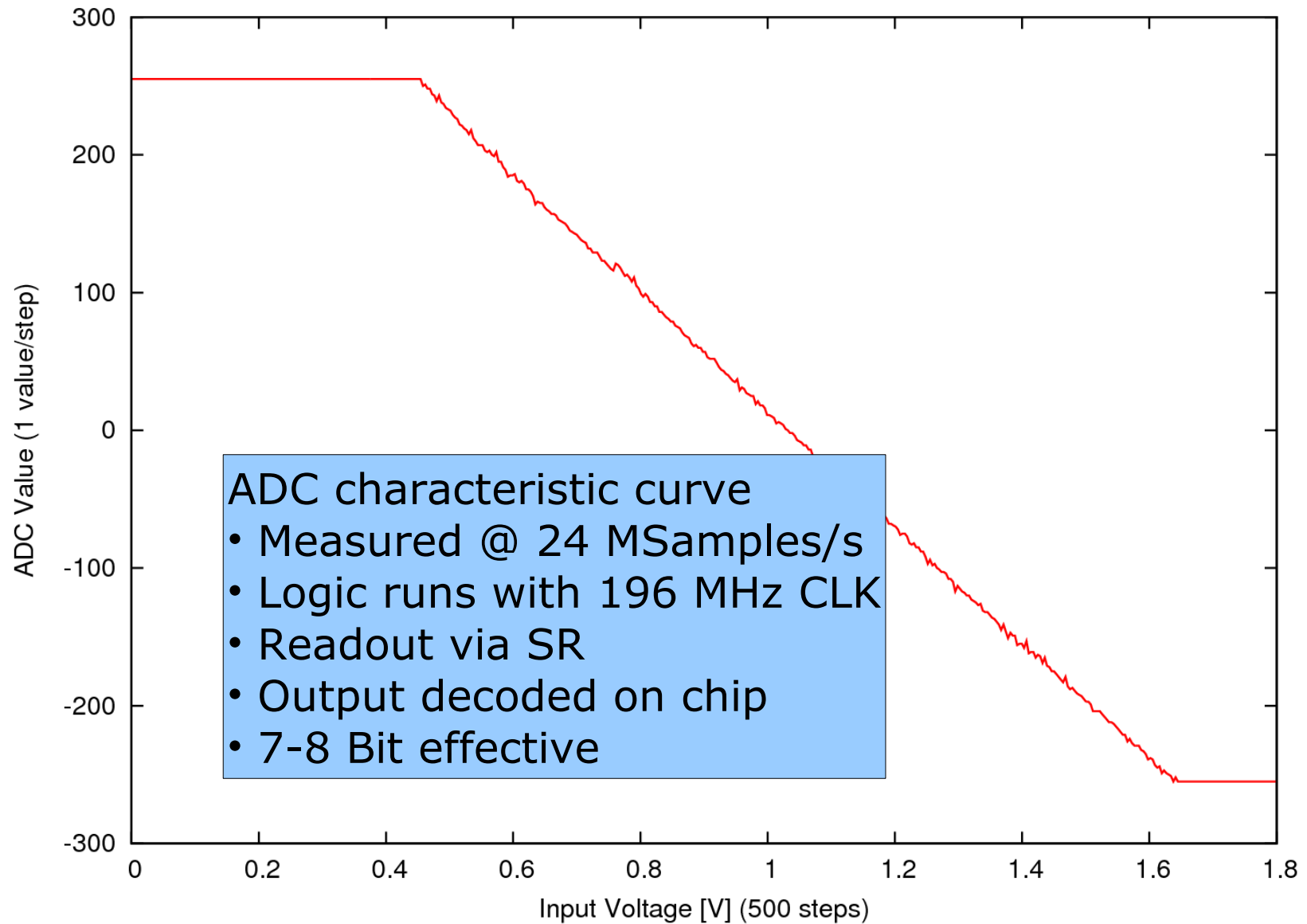
Preamp/Shaper Results

- Noise was measured with s-curve scans using the discriminator
- Injection capacitor calibrated via test circuit
- 4 different preamplifier types: old, normal, no triwell, long

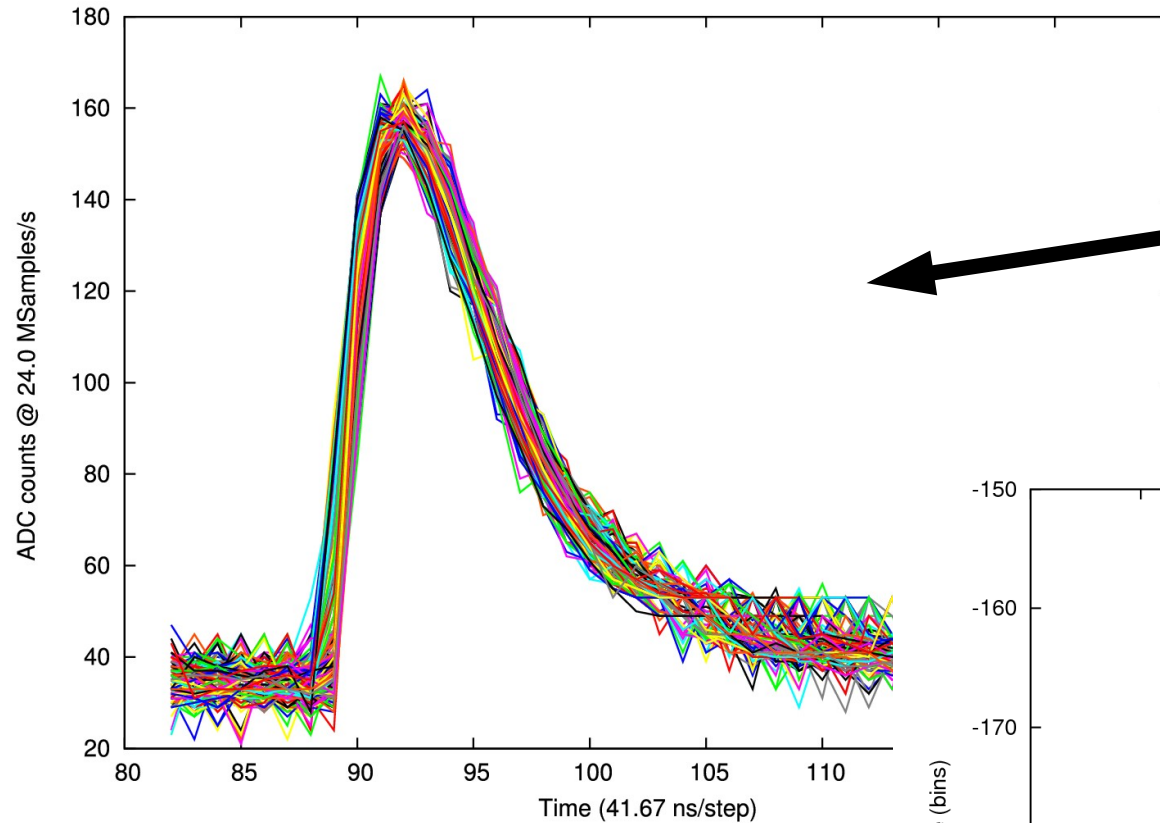


- Results:
 - Noise values of **normal** (triwell NMOS input, minimal length) and **no triwell** (NMOS without triwell, minimal length) channel show no significant difference compared to the old channel => values still much worse than simulated
 - Noise slope of **long** (triwell NMOS input, 320 nm length) channel about two-times smaller => about 800 e ENC @ 30 pF achievable, still worse than simulation

ADC Results

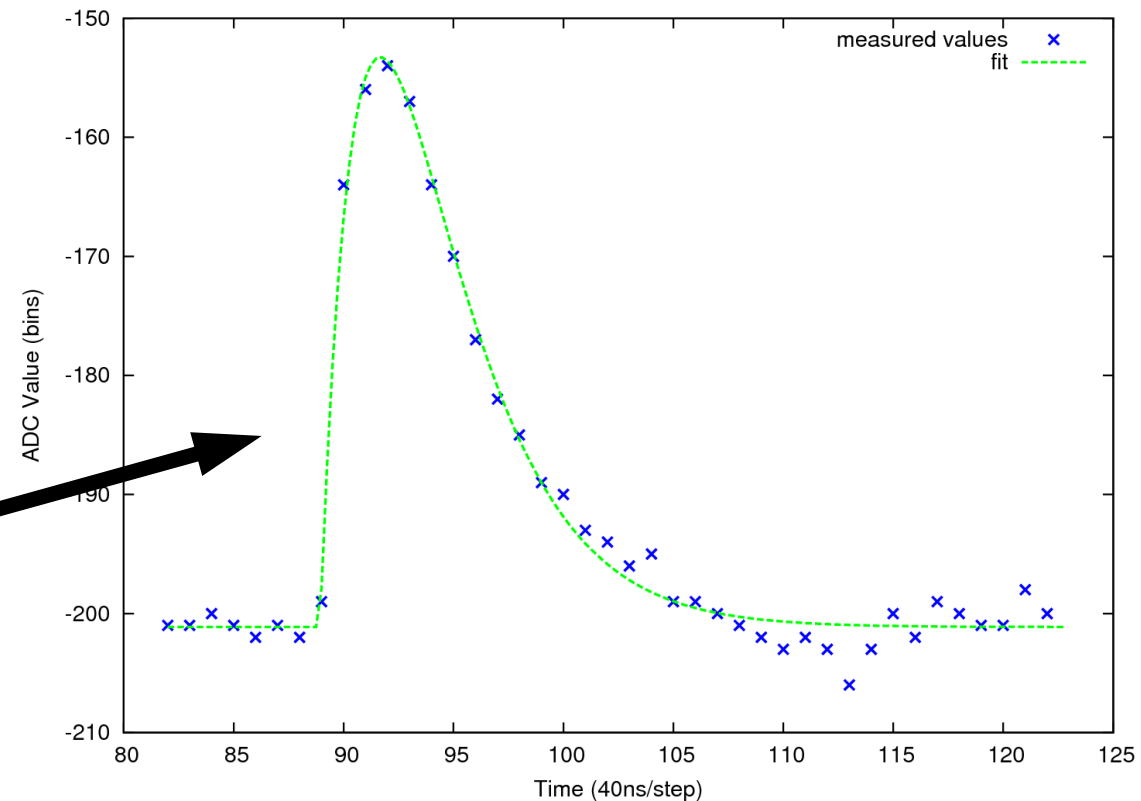


System: Shaper Output connected to ADC



Some ADCs can be connected to shaper outputs
→ digitization of shaper pulses possible (1000 hits shown here)

Theoretic and measured pulse shapes match well
(fitted with $x * \exp(-x)$)

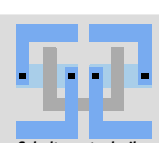


Summary

1x2 Mini@sic 0.18 μm UMC 1P6M Test-Chip (1.5x3.2 mm²)

- 26 preamp/shaper channels
 - 40 μm channel pitch (540 μm length)
 - 3.8 mW per channel
 - Shaper output pulse peaking-time 95 ns
 - 800 e ENC @ 30 pF detector capacitance (long channel)
- 8 pipelined ADCs
 - 9 Bit design, 7-8 Bit effective
 - 4.5 mW per ADC
 - 130x120 μm^2
 - 24 MSamples/s (has not been tested at faster speed yet)
- 5.3 kBit dynamic readout shift register matrix operates correctly
- 2 synthesized control and decoder blocks run with 196 MHz CLK
 - radiation-tolerant standard cells
 - “home-made” library

=> Whole chip works well!





Outlook: CBM/TRD Readout Chip V1.0

Ideas for the first complete readout chip



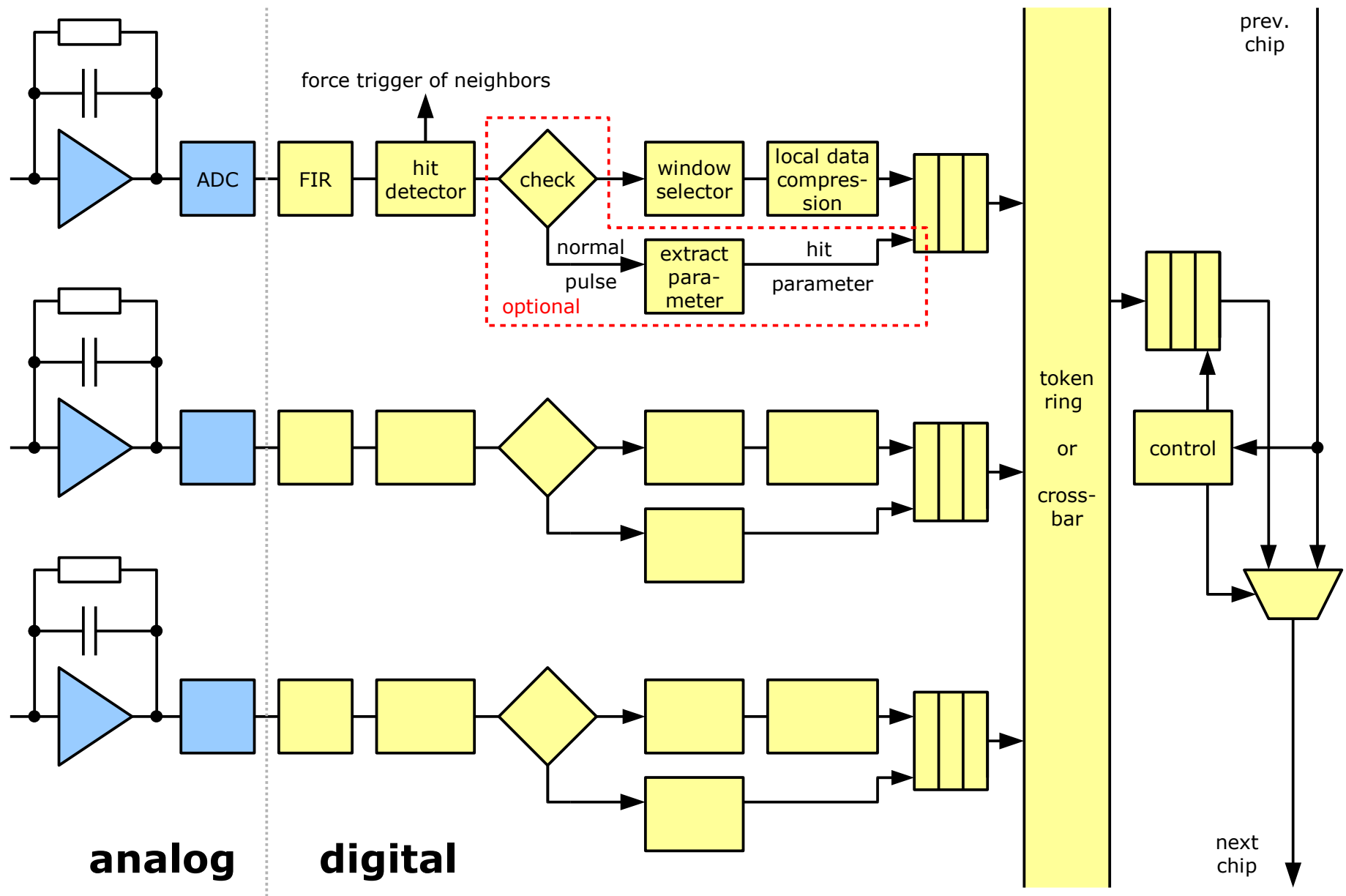
Tim Armbruster

tim.armbruster@ziti.uni-heidelberg.de

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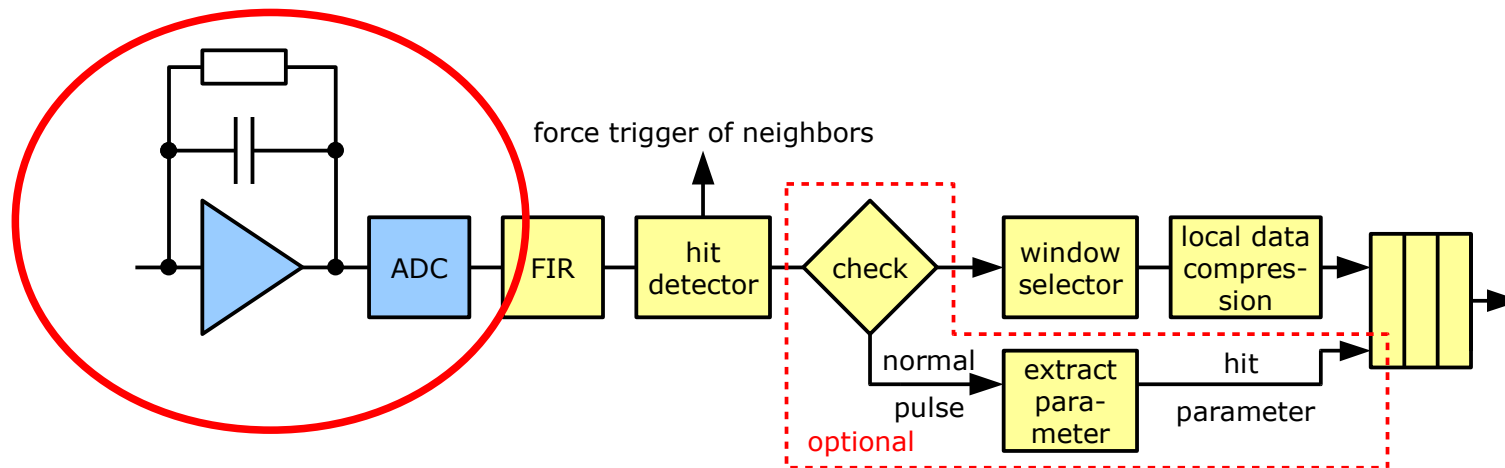
Preliminary Block Diagram



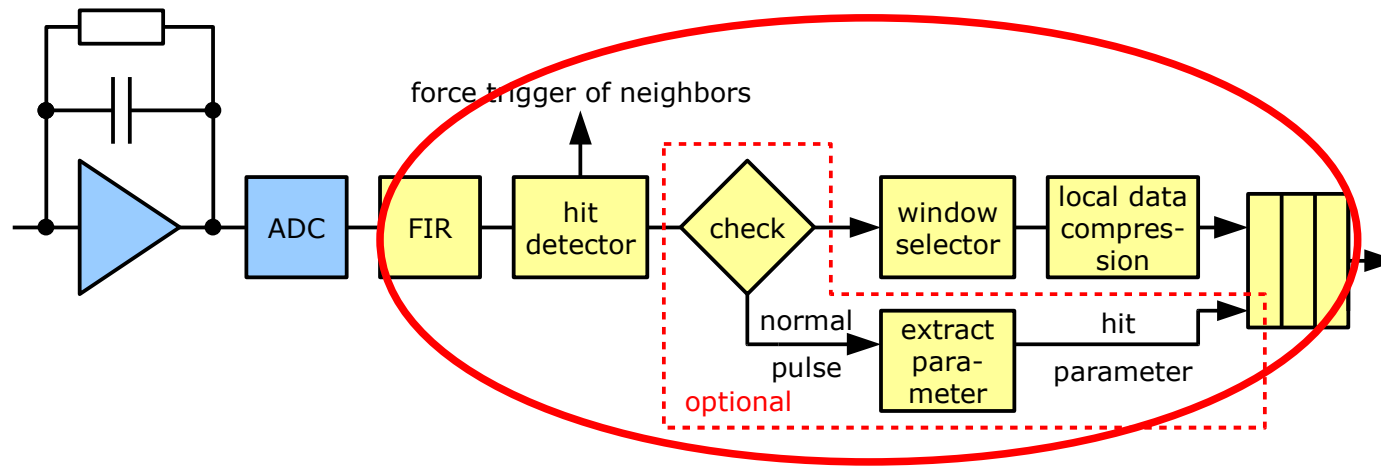
Analog Front-End

- Preamp/Shaper
 - Design as presented in previous talk(s), probably new layout needed to adjust pitch (benefit: more compact channels should be less sensitive to process variations)
 - Intended new feature: Switchable number of preamp-cells (adjustable tradeoff between amplifier noise and power consumption)
- ADC
 - Pipeline design mostly as presented in previous talk (8 Bit effective, 25 MSamples/s)
 - Control logic must be (re-)integrated into digital block

=> Detailed specification proposal will be finished soon



Digital Data Processing



- FIR filter stage, different tasks possible, for example:
 - 3rd/4th analog shaper
 - under/overshoot correction
- Hit detection unit ("digital discriminator")
 - detects valid hits, triggers packet generation
 - force trigger: force readout of neighbor channels
- Window selector
 - choose minimal but sufficient series of sample values
- Local data compression
 - due to high data rates data compression very reasonable (see next slides)
- Dynamic buffer / FIFO

Data-Rate Calculation (1/2)

Some estimated numbers:

- 32 channels / chip
- 250 kHz event rate / channel (one hit every 4 μ s)
- 8 Bit ADC resolution
- 10 samples / event
- 12 Bit time-stamp / event (epoch length 164 μ s @ 25MSamples/s ADC speed)
- 5 Bit channel ID

$$R_{chip} = \underbrace{\frac{250k \text{ events}}{\text{channel} \cdot s} \cdot 32 \text{ channels}}_{\text{hit rate chip}} \cdot \underbrace{\left(\frac{8 \text{ bit}}{\text{sample}} \cdot \frac{10 \text{ samples}}{\text{event}} \right)}_{\text{hit data}} + \underbrace{\frac{17 \text{ bit}}{\text{event}}}_{\text{time-stamp+ID}} = \frac{776 \text{ Mbit}}{s}$$

=> Conservative estimation: about 100 Bits/hit!

=> One 2.5 Gbit/s LVDS link could only be shared between 3 chips

But: Corner chips may produce much less than 250k events/s

Simple data compression unit reasonable

=> Epoch counter + forward error correction overhead not considered here!

Data-Rate Calculation (2/2)

Possible strategies for data-rate reduction:

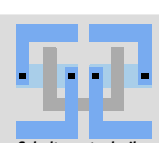
- Reduction of data
 - (Nearly) fixed: number of channels, event rate, ADC resolution (8-9 Bit), time-stamp resolution (10-12 Bit), channel ID
 - Potentially reducible: waveform data
 - 10 Samples/hit → 80 Bits/hit (8 Bit ADC) → main fraction of hit data
 - For curve fitting, less than 10 Samples/s may be sufficient. This depends strongly on curve shape and therefore on application/detector.
- Data compression
 - Further investigation on data compression strategies must be done
 - Compression potential due to data structure probably small

=> Very optimistic estimation (lower limit):

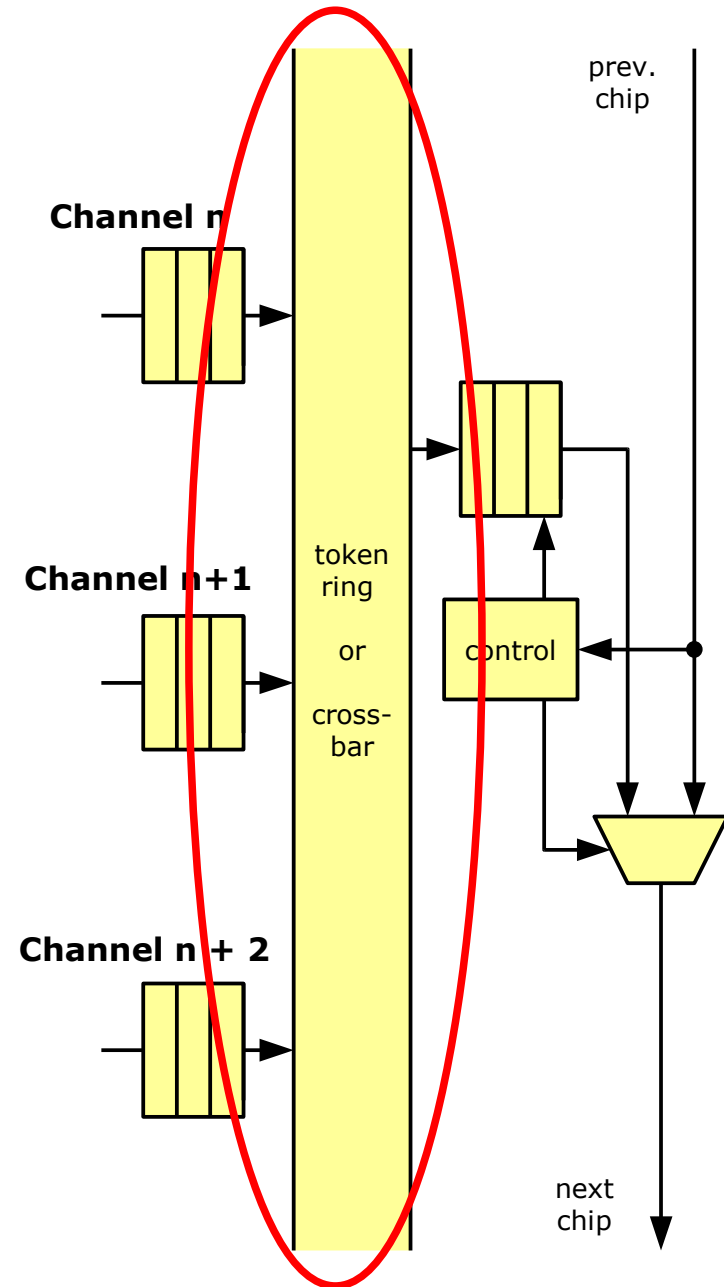
4 Samples/hit, data compression factor 80%

→ Still about 50 Bits/hit

→ 12.5MBit per second and channel

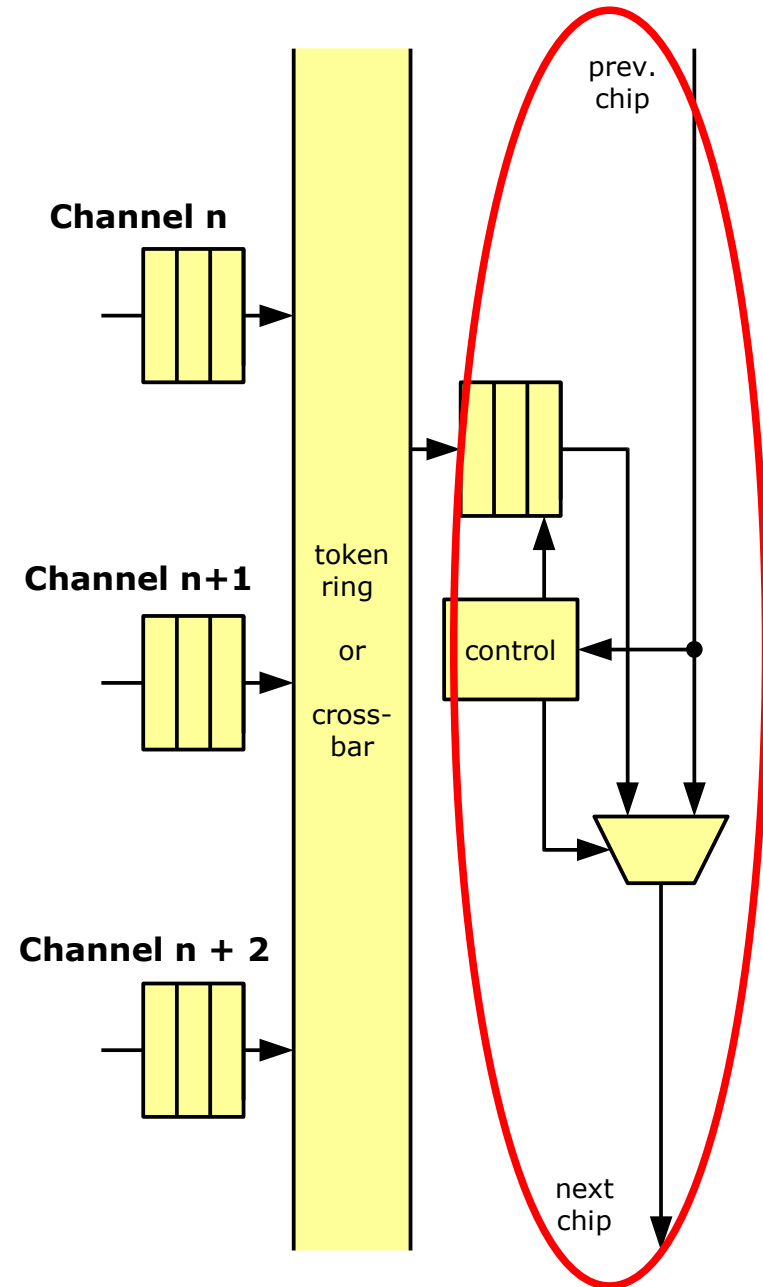


Inter-Channel Network



Data transfer from channels to output logic

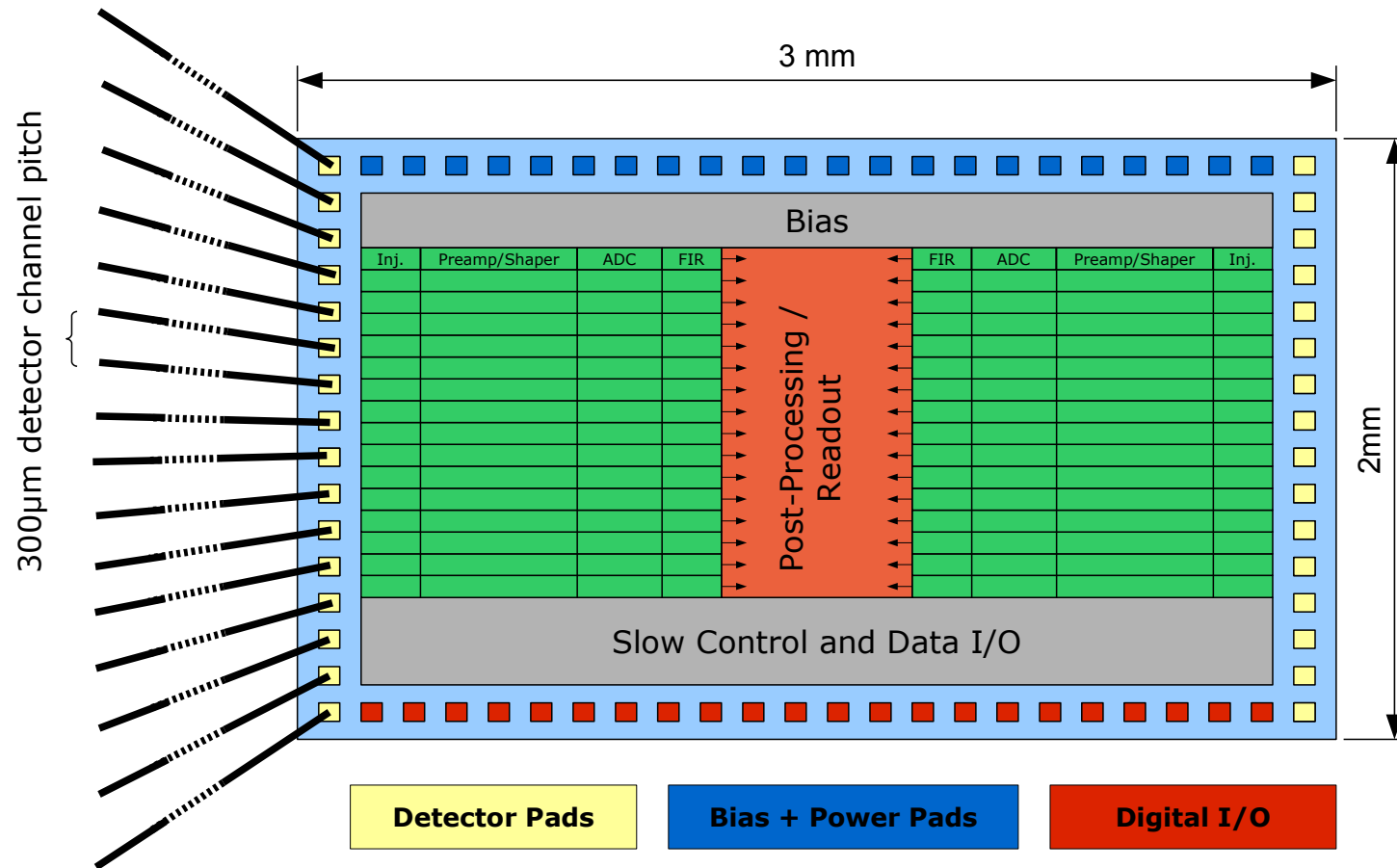
- Token ring network seems to be “fairest” solution
- n-XYTER serves as good example
- Think about subdividing one large ring in several smaller rings (e.g. two rings, 16 channels each):
 - small maximal token delay
 - simple arbiter/multiplexer between the small token rings should be easy to design, could be used for some additional load balancing
 - short(er) data buses
 - parallel design: token would have more time to “choose” next channel, could think about some kind of simple priority mechanism



Data transfer in-between chips and from chip to the outer world

- Data rates of one chip smaller than typical data-rate of common LVDS link (e.g. 2.5 GBits/s) → share one LVDS driver cell between several chips
- Simple proposal:
 - Connect n chips in series
 - First chip (initial mode): Loop: Create and send n-1 empty packets, send 1 data package, ... (LVDS driver in low strength / low power mode)
 - Middle chip (pass mode): Loop: Pass n-1 packets, replace one empty packet with data, ... (LVDS driver in low strength mode)
 - Last chip (driver mode): Loop: Pass n-1 packets, replace last empty packet with own data, ... (LVDS driver in high strength mode) → last chip drives transmission line

Preliminary Floorplan



- 3 x 2 mm² estimated die size
- 32 channels, 40-80µm pitch, (mostly) symmetric layout, low(er) IR-drops
- Detector connection-pads on two sides (chips will probably be attached to back of detector-module, this relaxes routing/spacing)
- Next/first (very important) step: Find good pin and power routing strategy



Simple electric data transmission

Or: How far can we go with copper?



Marco Oster, Tim Armbruster

tim.armbruster@ziti.uni-heidelberg.de

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The question arose some time ago: Why not using copper cables for data transmission from front-end chips to DAQ?

=> Big advantages:

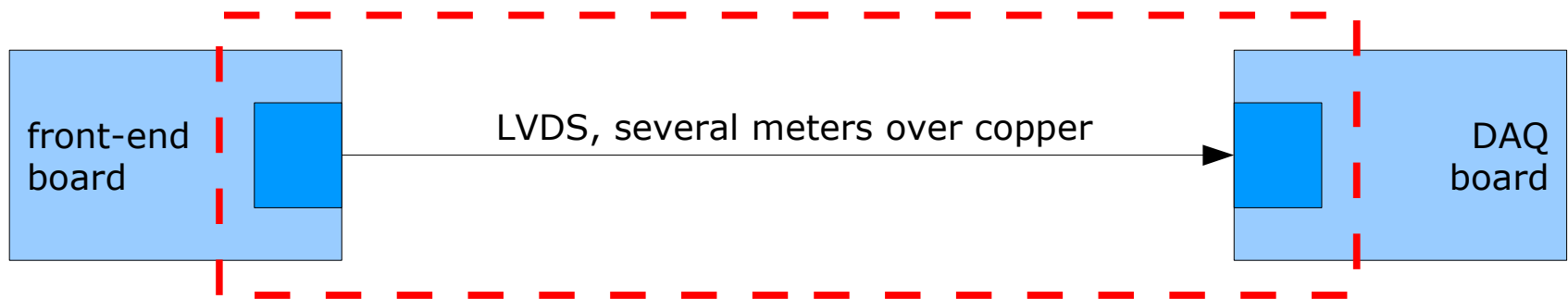
- No need of large and non-radhard optical transceiver modules
- Much simpler to connect and handle front-end devices
- ...

Therefore we've started a study to figure out how far we can go with moderate effort.

Project goal: Build a simple UMC018 transmitter cell which encodes to a minimal Xilinx Aurora protocol and which is able to drive over some meters of copper (into a Xilinx multi gigabit transceiver (MGT)).

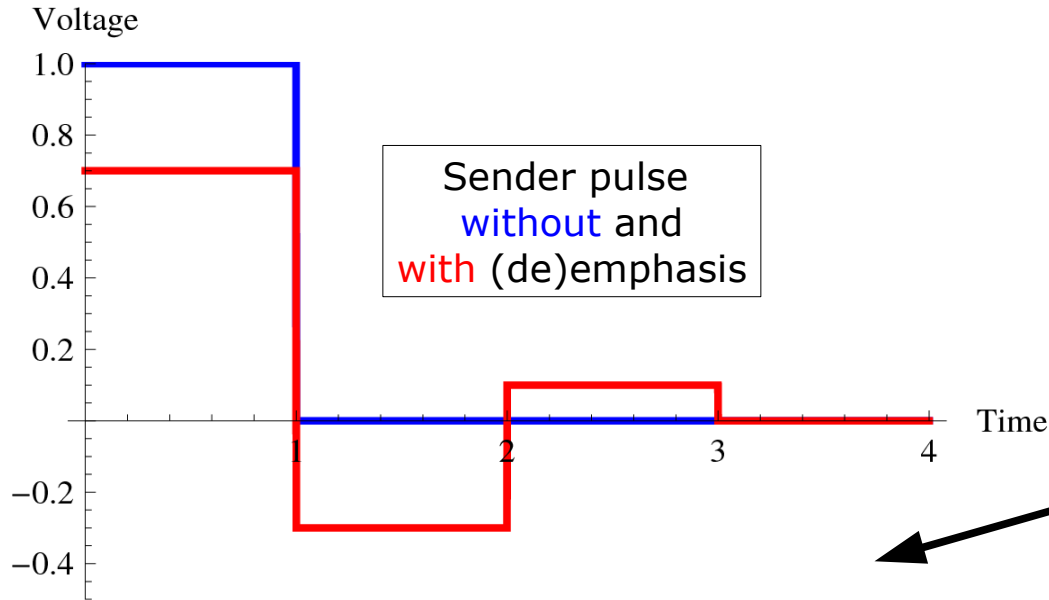
Stoyan Todorov's and Marco Oster's Diploma Thesis

- Part 1 (Stoyan Todorov): Design of a minimal Aurora protocol cell
 - Verilog modules have been finished and tested successfully via FPGA
 - Aurora module has been synthesized and submitted (not tested yet)
- New: Part 2 (Marco Oster): Physical design space exploration
 - Gain experience in modeling and simulating simple transmission lines
 - Gather information about available cable types and their behavior
 - Study different emphasis/equalization techniques
 - Build and submit a simple LVDS transmission circuit
 - Evaluate chip results (still in progress)
- Future plan: Part 3: Build complete transmission channel

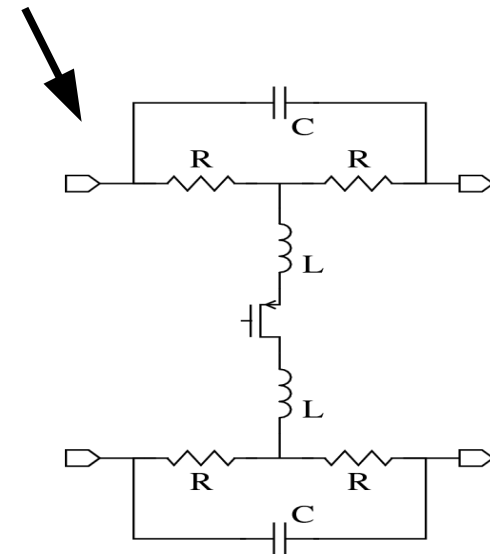
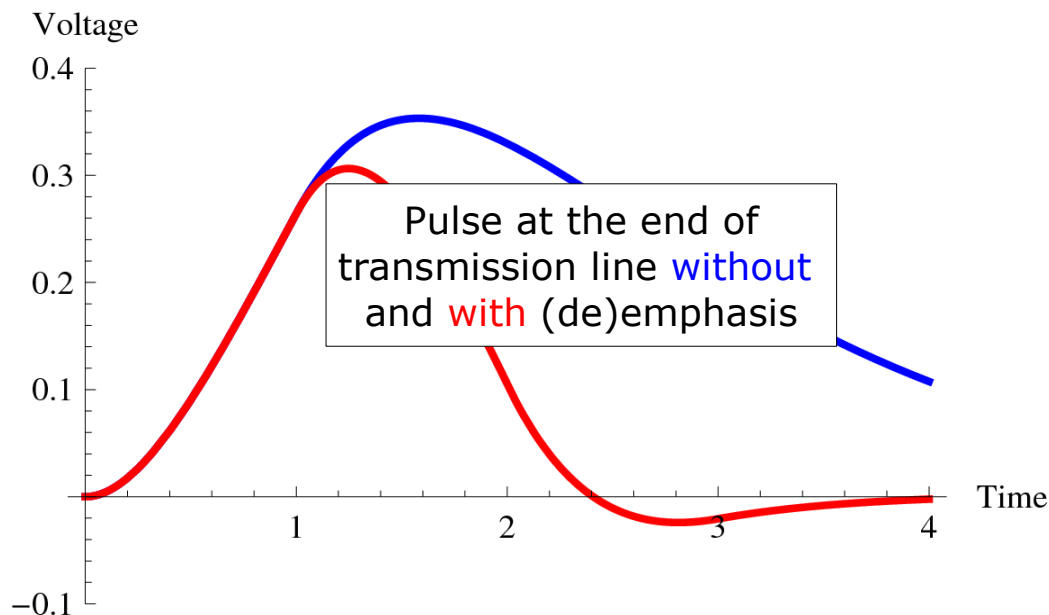


Emphasis: Simple simulation

Emphasis: Signal modulation in sender

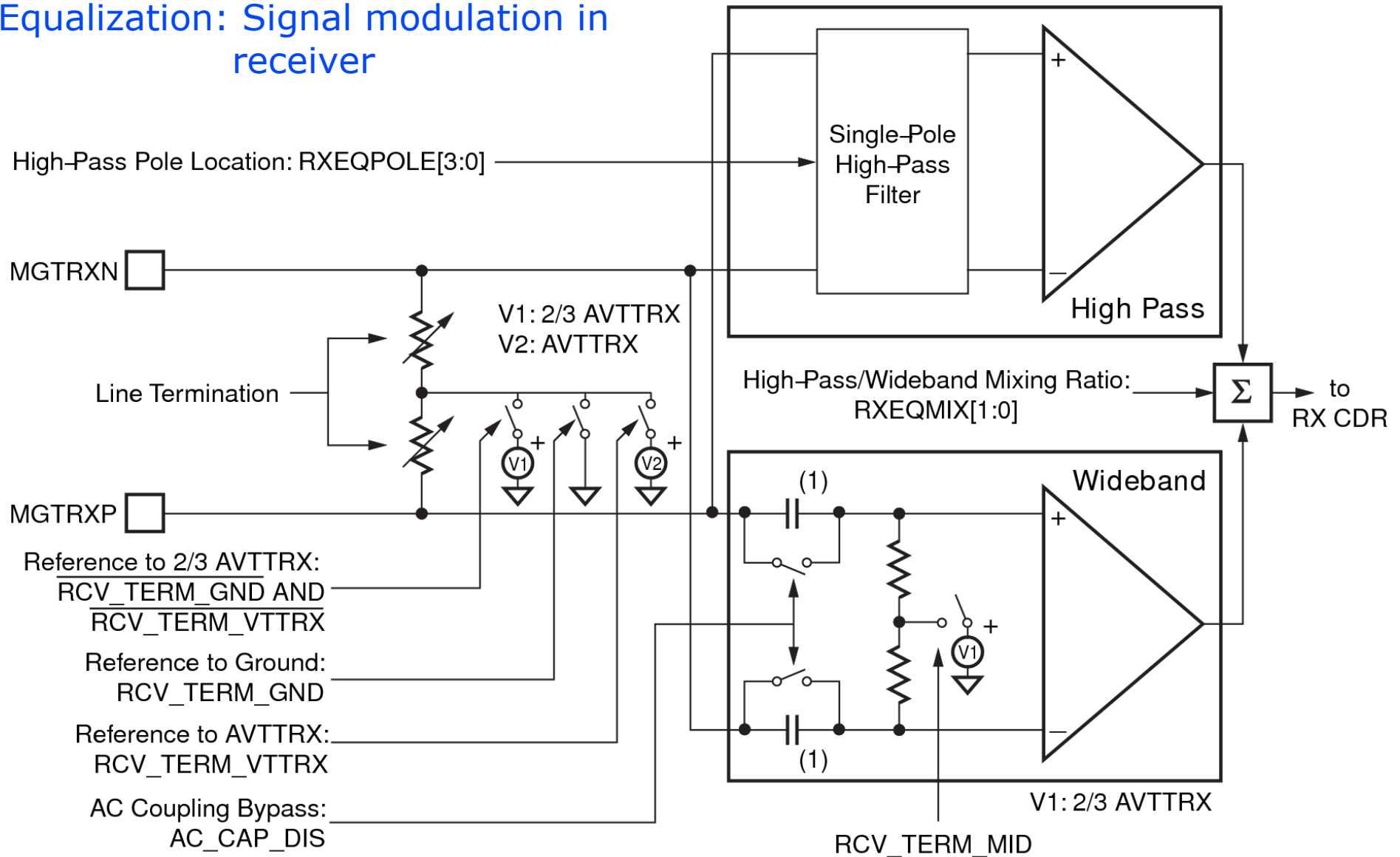


- With little effort, pulse length can be significantly reduced → higher data rates
- Two basic methods:
 - Logical, e.g. via FIR filter
 - Analog, e.g. high frequency boosting by using a passive "RCL" network:

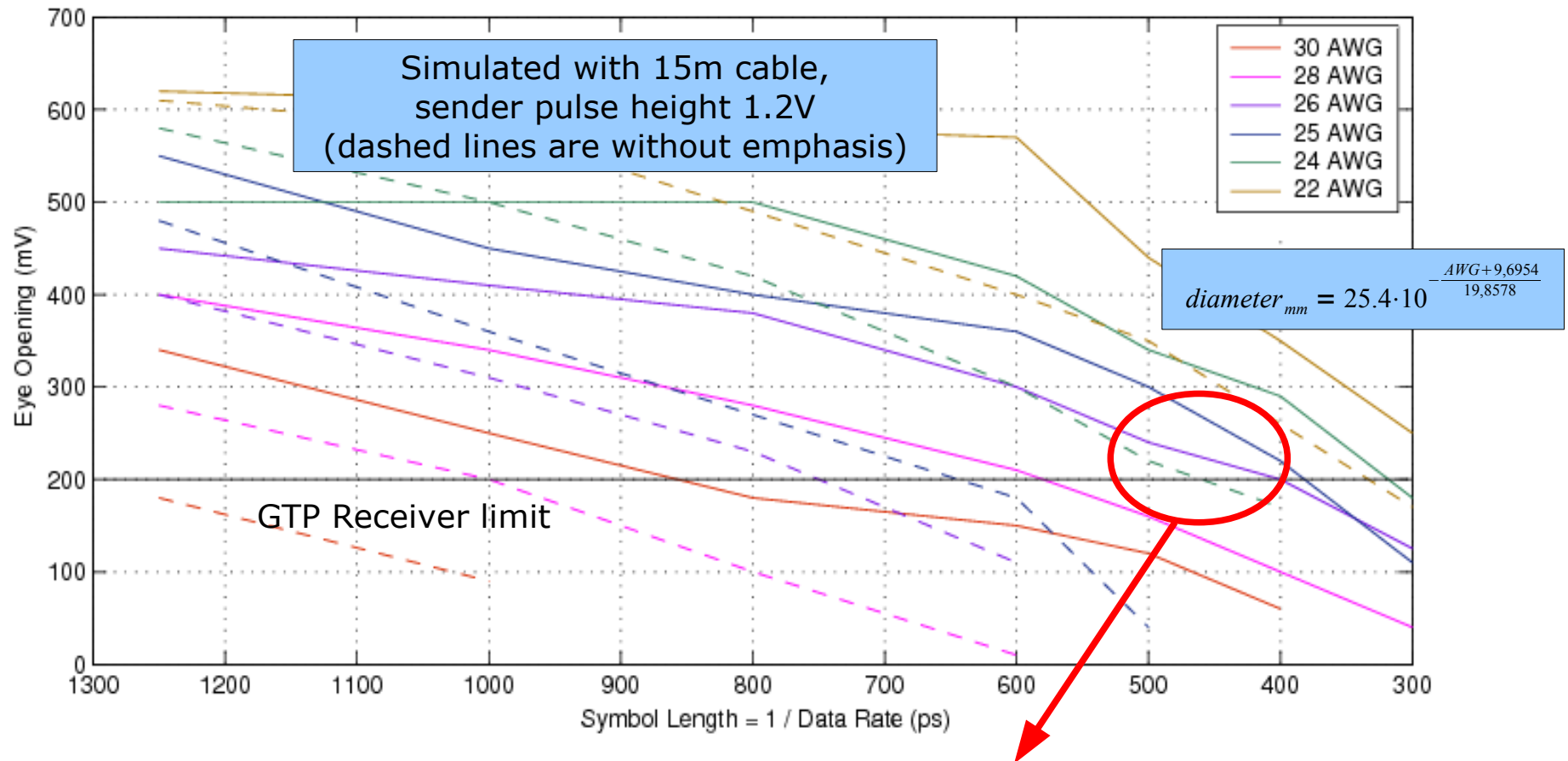


Equalization-Example: GTP/GTX Receiver of Virtex5

Equalization: Signal modulation in receiver



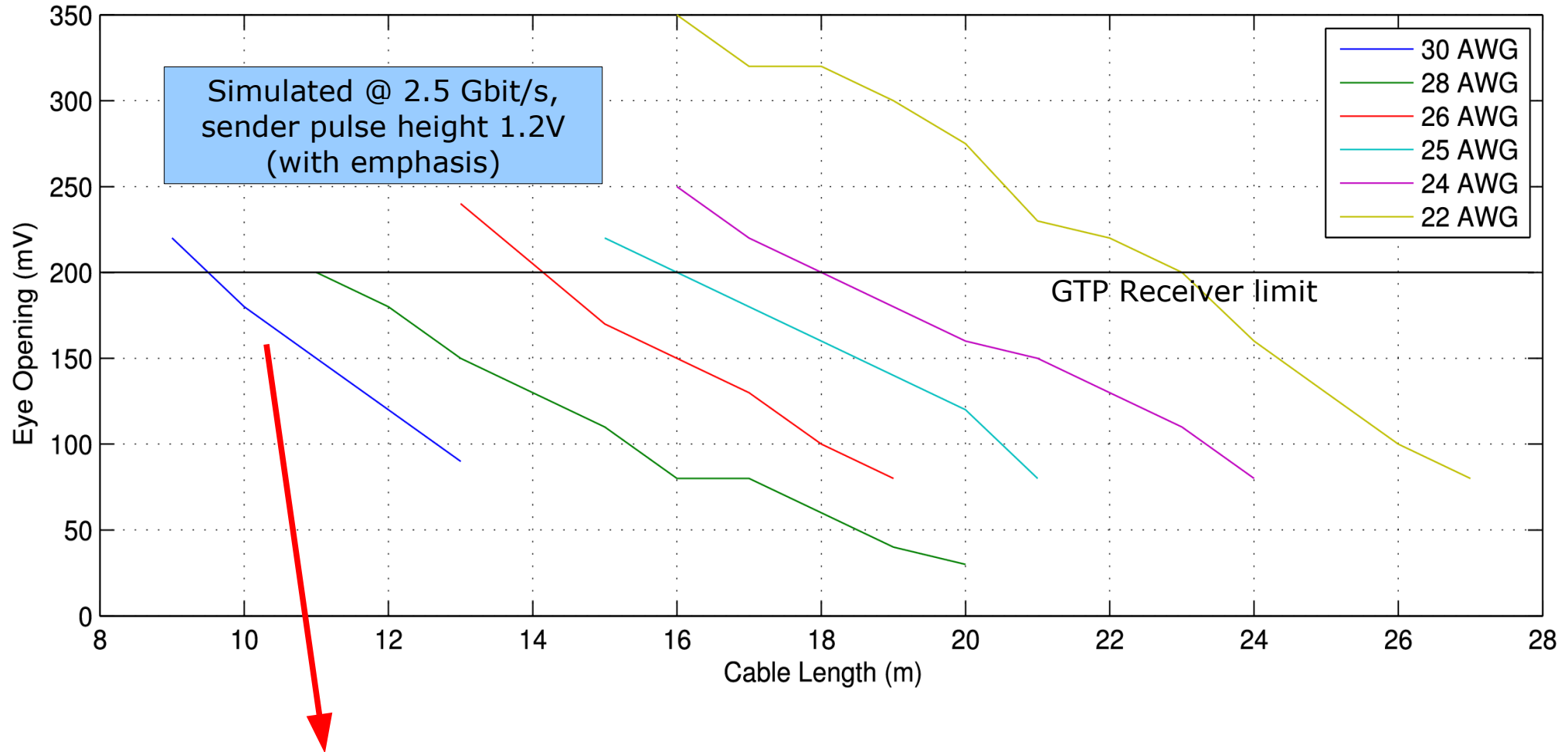
Cable Simulations (1/2)



For example: 2GBit/s over 15m with AWG 26 (0.4mm diameter) should be receivable by Xilinx GTP (order of magnitude)

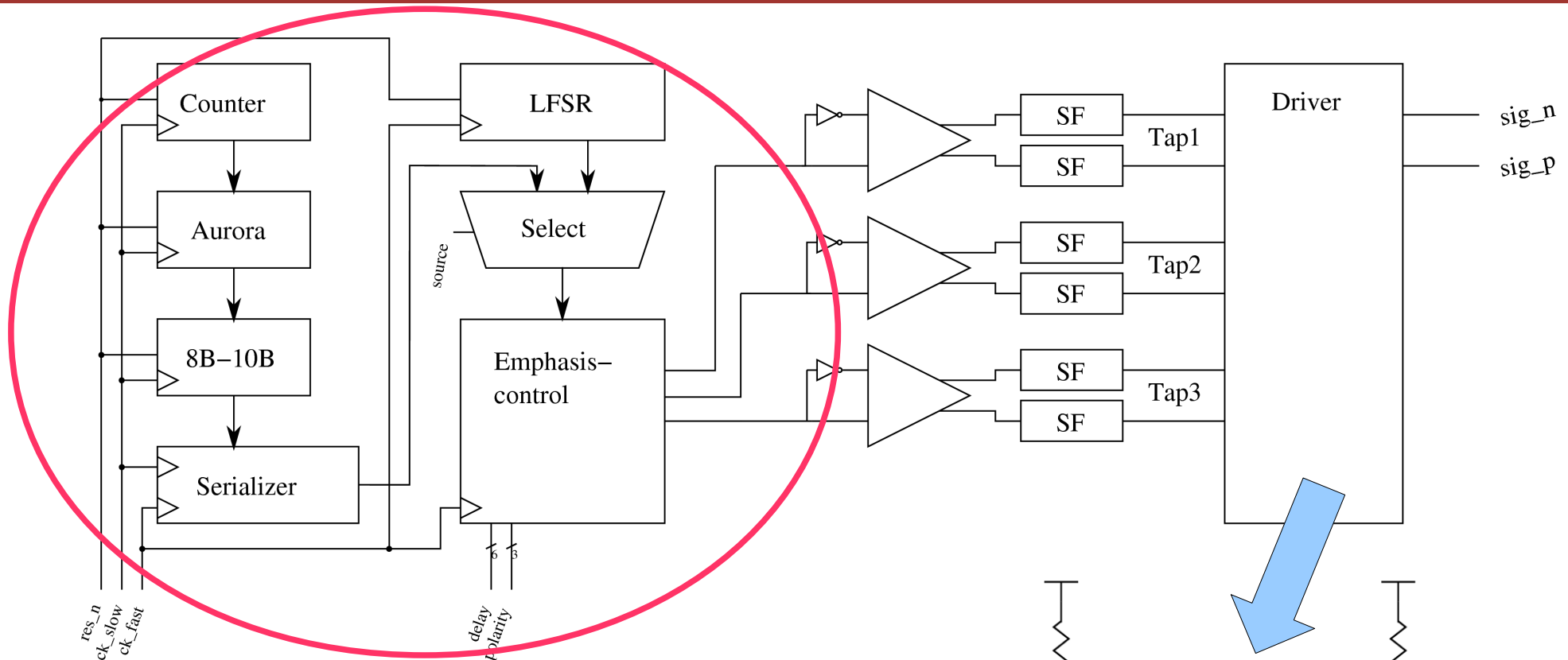
Note: Cable models were fitted using the data sheet parameters

Cable Simulations (2/2)



For example: 2.5Gbit/s over 10m should already be receivable when using a AWG 28 cable (0.32mm diameter)

Test Circuit Design Overview (UMC018)

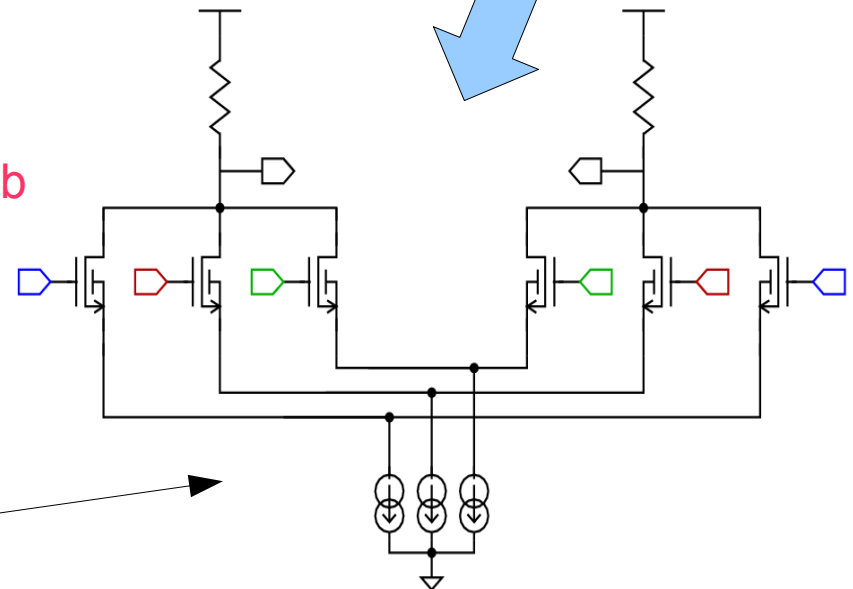


Synthesized using our
rad-hard standard-cell lib

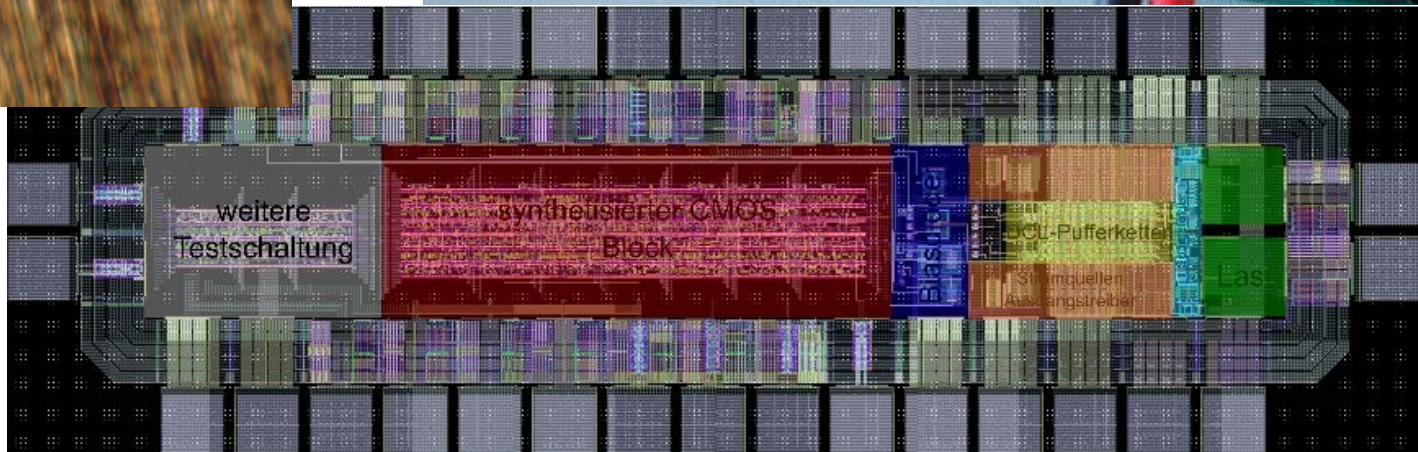
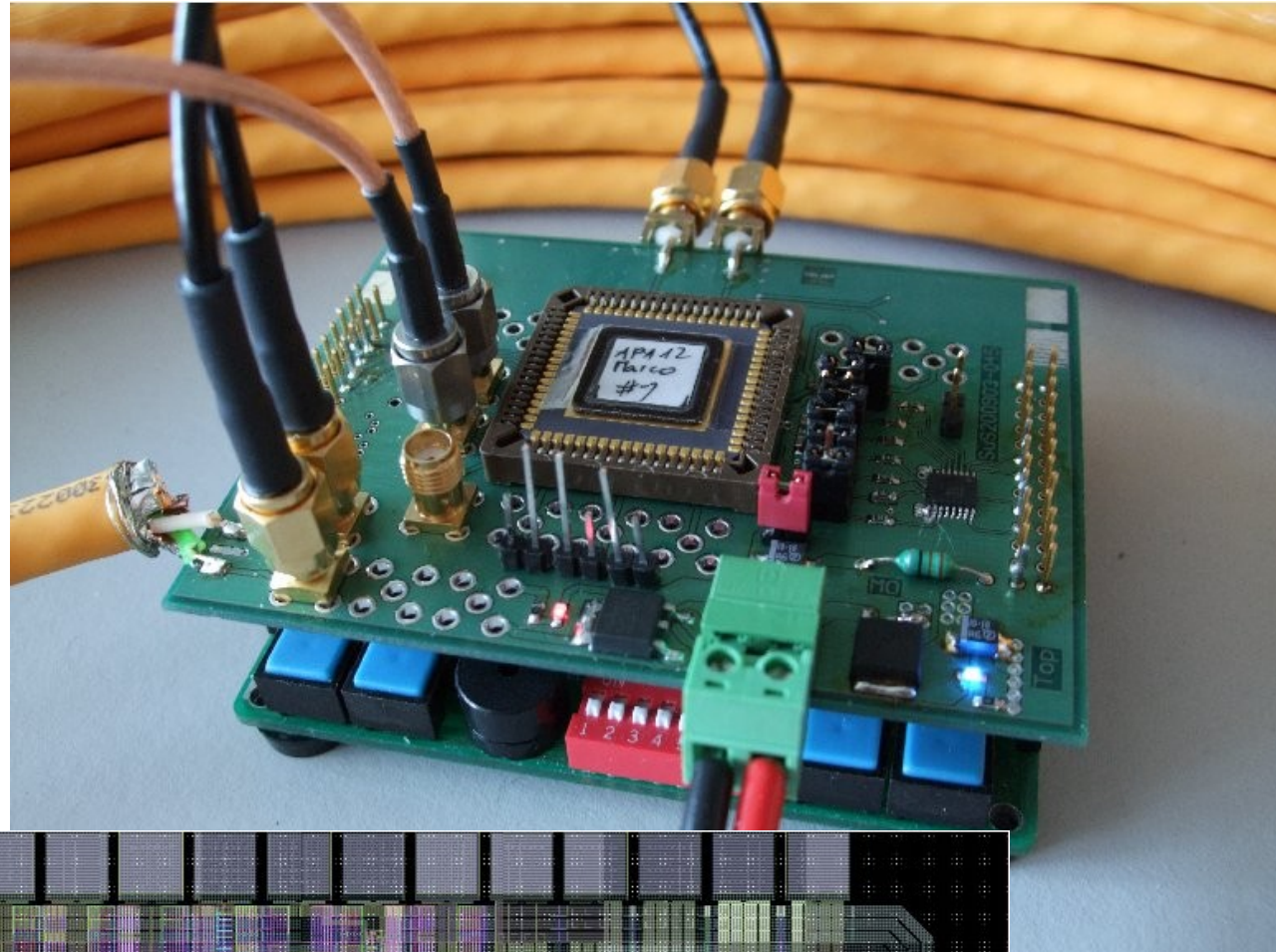
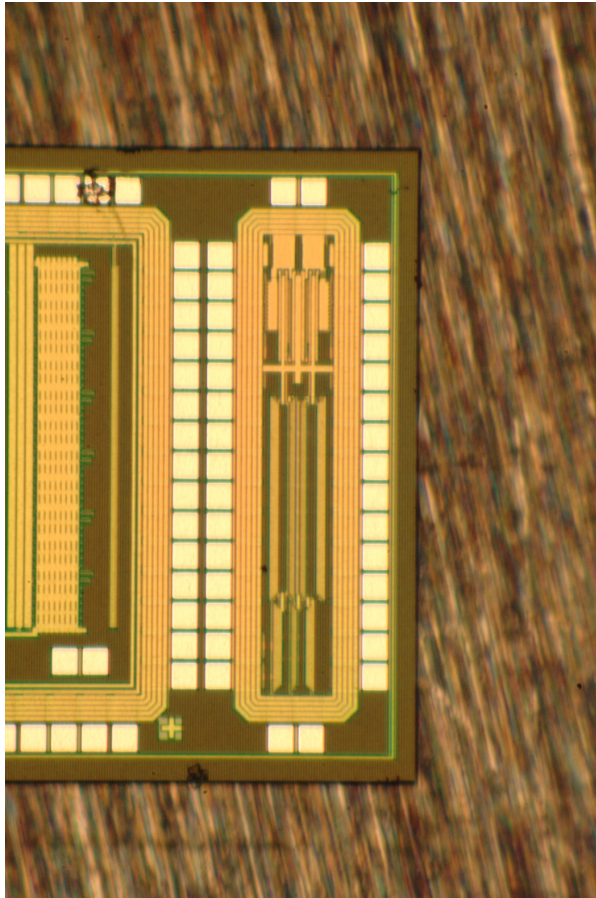
Two test cases:

- Simple LFSR
- Counter encoded to Aurora protocol

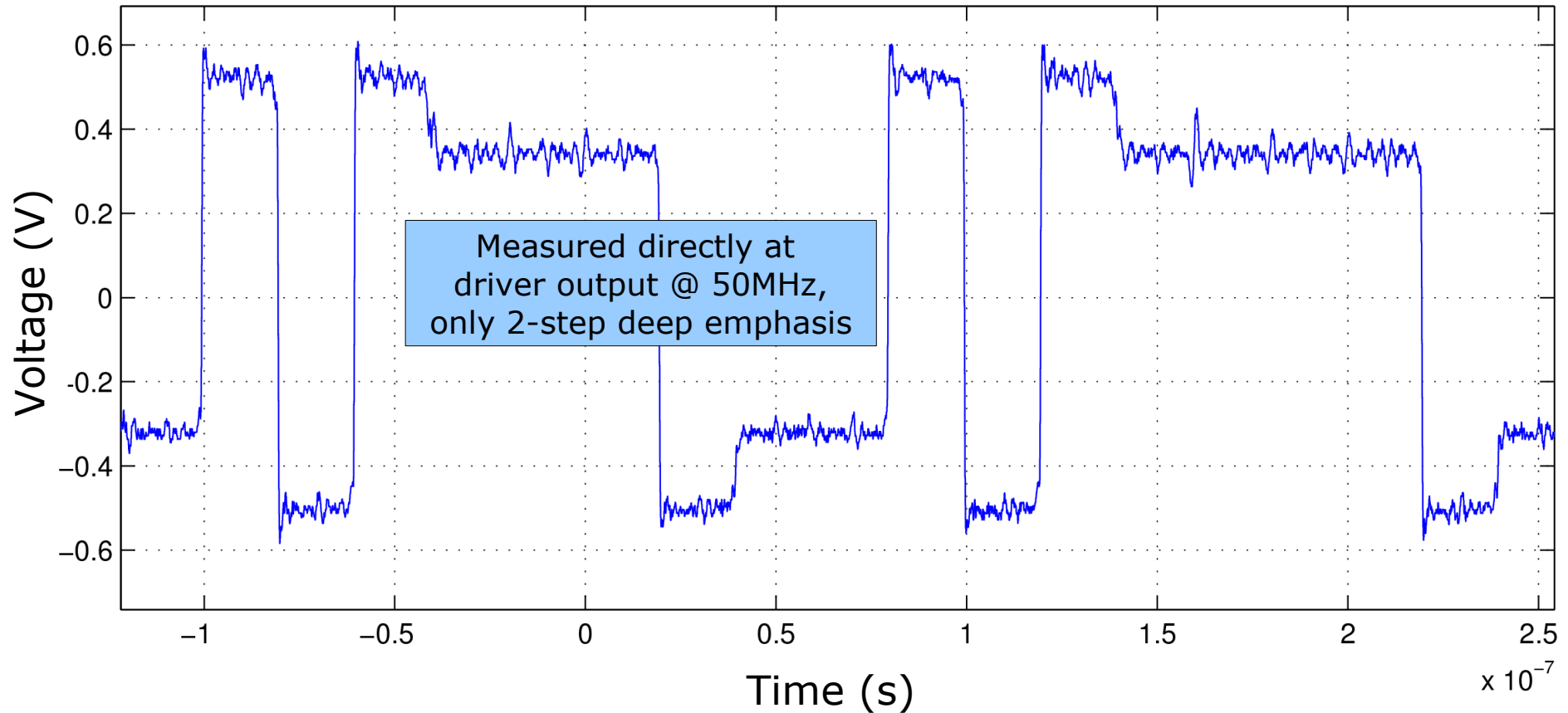
Emphasis realized with three weight stages (FIR filter implementation)



Layout and Test Setup



Measured Buffer Output with Deemphasis



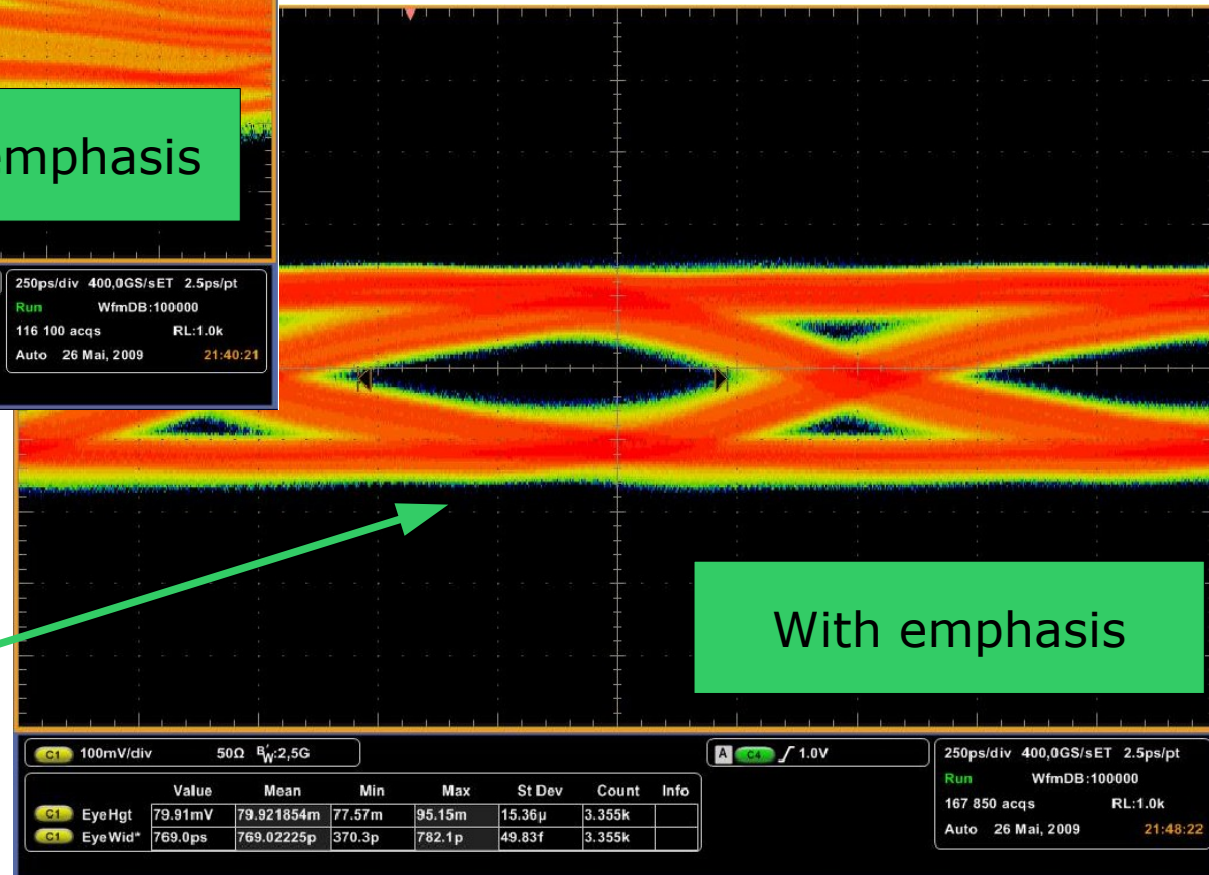
First Result: Eye Diagram after 42m

measured with 42m
cable @ 750MBit/s

Without emphasis

With emphasis

eye opening about 80mV



Aurora protocol

- Minimal encoding block has been designed and simulated successfully
- Synthesized and submitted cell available but not tested yet

Physical transmission

- Gained basic knowledge of transmission techniques
- Several cable models and simulation setups available
- Test-chip/test-driver works but is not fully tested yet
- 2.5GBit/s over 10m should be achievable with moderate effort

=> Copper cable seems to be a reasonable alternative to optical data transmission, further analysis is being performed.

Thank you!

